

Topical Collection

Feature Innovation Papers

Message from the Collection Editor

This is a collection of top quality papers from the editorial board members, or those who have been invited by the editorial office and the Editor-in-Chief. The topics include:

- New innovation ideas
- New innovation technologies
- New innovation products

The papers should be research papers (or review papers) with the detailed description and verification of the author's own work.

Collection Editor

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Message from the Editorial Board

The unique journal *Inventions* is different from all other journals. Many scholars spend their lives publishing research papers in many different journals, but most of these journals do not help scholars collate and analyze their results or assist in promoting them to a relevant industry. However, *Inventions* will help authors not only to publish their papers in the journal, but also to promote their research results to industry and assist them in realizing the purpose of technology transfer. In the future, *Inventions* will help authors to evaluate their technology license fees based on the valuation theory and approaches and also help authors to show their patents and technologies on a network transaction platform.

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